

**TIDA01402 REV E1 Bill of Materials**

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB1	1		TIDA01042	Any	Printed Circuit Board	
5.5V, 5V	2		5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
C2, C4, C6, C12	4	0.1uF	06033D104KAT2A	AVX	CAP, CERM, 0.1 µF, 25 V, +/- 10%, X5R, 0603	0603
C8, C9, C10	3	1uF	C1608X5R1H105K080AB	TDK	CAP, CERM, 1 µF, 50 V, +/- 10%, X5R, 0603	0603
C11	1	10uF	293D106X0010A2TE3	Vishay-Sprague	CAP, TA, 10 µF, 10 V, +/- 20%, 3.4 ohm, SMD	3216-18
C13	1	10uF	C2012X5R1E106K125AB	TDK	CAP, CERM, 10 µF, 25 V, +/- 10%, X5R, 0805	0805
DAC_OUT, Output	2		5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
FID1, FID2, FID3	3		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
GND1, GND2, GND3	3		5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
H9, H10, H11, H12	4		SJ-5303 (CLEAR)	3M	Bumpon, Hemisphere, 0.44 X 0.20, Clear	Transparent Bumpon
J1, J7	2		ED555/2DS	On-Shore Technology	Terminal Block, 3.5mm Pitch, 2x1, TH	7.0x8.2x6.5mm
J2	1		PEC04SAAN	Sullins Connector Solutions	Header, 100mil, 4x1, Tin, TH	Header, 4x1, 100mil, TH
J3	1		851-43-010-20-001000	Mill-Max	Receptacle, 50mil, 10x1, Gold, R/A, TH	receptacle 10x1, 50mil
J4	1		TSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	3x1 Header
J5, J6	2		TSW-103-07-G-D	Samtec	Header, 100mil, 3x2, Gold, TH	3x2 Header
R1, R2, R3	3	0	RC0603JR-070RL	Yageo America	RES, 0, 5%, 0.1 W, 0603	0603
R7	1	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
U1	1		DAC8830IBDR	Texas Instruments	16-Bit, Ultra-Low Power, Voltage-Output Digital-to-Analog Converter, D0008A (SOIC-8)	D0008A
U2	1		REF5050AID	Texas Instruments	Low Noise, Very Low Drift, Precision Voltage Reference, -40 to 125 degC, 8-pin SOIC (D), Green (RoHS & no Sb/Br)	D0008A
U4	1		OPA388IDR	Texas Instruments	Precision, Zero-Drift, Zero-Crossover, True Rail-to-Rail Input/Output, Operational Amplifier, D0008A (SOIC-8)	D0008A
U5	1		OPA340UA	Texas Instruments	Single-Supply, Rail-to-Rail Operational Amplifier MicroAmplifier(TM) Series, 2.7 to 5.5 V, -40 to 85 degC, 8-pin SOIC (D0008A), Green (RoHS & no Sb/Br)	D0008A
C1	0	0.1uF	06033D104KAT2A	AVX	CAP, CERM, 0.1 µF, 25 V, +/- 10%, X5R, 0603	0603
C3, C5	0	0.012uF	GRM188R71E123KA01D	MuRata	CAP, CERM, 0.012 µF, 25 V, +/- 10%, X7R, 0603	0603
C7	0	1uF	C1608X5R1H105K080AB	TDK	CAP, CERM, 1 µF, 50 V, +/- 10%, X5R, 0603	0603
U3	0		OPA333AIDBVT	Texas Instruments	17 uA, MicroPower, Precision, Zero Drift CMOS Operational Amplifier, 1.8 to 5.5 V, -40 to 125 degC, 5-pin SOT23 (DBV0005A), Green (RoHS & no Sb/Br)	DBV0005A

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